

January 2008

74AC374, 74ACT374 Octal D-Type Flip-Flop with 3-STATE Outputs

Features

- I_{CC} and I_{OZ} reduced by 50%
- Buffered positive edge-triggered clock
- 3-STATE outputs for bus-oriented applications
- Outputs source/sink 24mA
- See 273 for reset version
- See 377 for clock enable version
- See 373 for transparent latch version
- See 574 for broadside pinout version
- See 564 for broadside pinout version with inverted outputs
- ACT374 has TTL-compatible inputs

General Description

The AC/ACT374 is a high-speed, low-power octal D-type flip-flop featuring separate D-type inputs for each flip-flop and 3-STATE outputs for bus-oriented applications. A buffered Clock (CP) and Output Enable (OE) are common to all flip-flops.

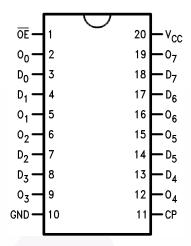
Ordering Information

Order Number	Package Number	Package Description
74AC374SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74AC374SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74AC374MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74AC374PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
74ACT374SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74ACT374SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ACT374MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
74ACT374MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74ACT374PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagram



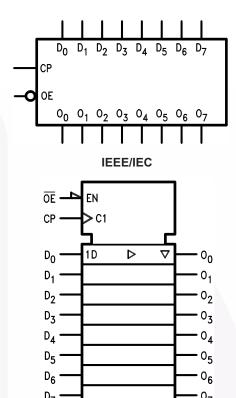
Pin Description

Pin Names	Description
D ₀ –D ₇	Data Inputs
СР	Clock Pulse Input
ŌĒ	3-STATE Output Enable Input
O ₀ -O ₇	3-STATE Outputs

Functional Description

The AC/ACT374 consists of eight edge-triggered flipflops with individual D-type inputs and 3-STATE true outputs. The buffered clock and buffered Output Enable are common to all flip-flops. The eight flip-flops will store the state of their individual D inputs that meet the setup and hold time requirements on the LOW-to-HIGH Clock (CP) transition. With the Output Enable (\overline{OE}) LOW, the contents of the eight flip-flops are available at the outputs. When the \overline{OE} is HIGH, the outputs go to the high impedance state. Operation of the \overline{OE} input does not affect the state of the flip-flops.

Logic Symbols



Truth Table

	Outputs		
D _n	СР	ŌĒ	O _n
Н	<i></i>	L	Н
L	<i></i>	L	L
Х	Х	Н	Z

H = HIGH Voltage Level

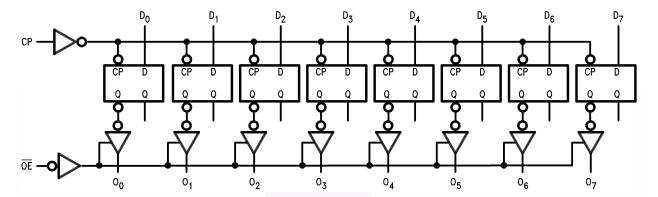
L = LOW Voltage Level

X = Immaterial

Z = High Impedance

✓ = LOW-to-HIGH Transition

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	-0.5V to +7.0V
I _{IK}	DC Input Diode Current	
	$V_{I} = -0.5V$	-20mA
	$V_{I} = V_{CC} + 0.5$	+20mA
V _I	DC Input Voltage	-0.5V to V _{CC} + 0.5V
I _{OK}	DC Output Diode Current	
	$V_{O} = -0.5V$	-20mA
	$V_{O} = V_{CC} + 0.5V$	+20mA
Vo	DC Output Voltage	-0.5V to V _{CC} + 0.5V
Io	DC Output Source or Sink Current	±50mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current per Output Pin	±50mA
T _{STG}	Storage Temperature	−65°C to +150°C
T _J	Junction Temperature	140°C

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	
	AC	2.0V to 6.0V
	ACT	4.5V to 5.5V
VI	Input Voltage	0V to V _{CC}
V _O	Output Voltage	0V to V _{CC}
T _A	Operating Temperature	-40°C to +85°C
ΔV / Δt	Minimum Input Edge Rate, AC Devices:	125mV/ns
	V_{IN} from 30% to 70% of V_{CC} , V_{CC} @ 3.3V, 4.5V, 5.5V	
ΔV / Δt	Minimum Input Edge Rate, ACT Devices:	125mV/ns
	V _{IN} from 0.8V to 2.0V, V _{CC} @ 4.5V, 5.5V	

DC Electrical Characteristics for AC

				T _A = -	+25°C	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	
Symbol	Parameter	V _{CC} (V)	Conditions	Тур.	G	uaranteed Limits	Units
V _{IH}	Minimum HIGH Level	3.0	$V_{OUT} = 0.1V$ or	1.5	2.1	2.1	V
	Input Voltage	4.5	V _{CC} – 0.1V	2.25	3.15	3.15	
		5.5		2.75	3.85	3.85	
V _{IL}	Maximum LOW Level	3.0	$V_{OUT} = 0.1V$ or	1.5	0.9	0.9	V
	Input Voltage	4.5	V _{CC} – 0.1V	2.25	1.35	1.35	
		5.5		2.75	1.65	1.65	
V _{OH}	Minimum HIGH Level	3.0	$I_{OUT} = -50\mu A$	2.99	2.9	2.9	V
	Output Voltage	4.5		4.49	4.4	4.4	
		5.5		5.49	5.4	5.4	
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -12\text{mA}$		2.56	2.46	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}$		3.86	3.76	
	5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}^{(1)}$		4.86	4.76		
V _{OL}	Maximum LOW Level	3.0	$I_{OUT} = 50\mu A$	0.002	0.1	0.1	V
	Output Voltage	4.5		0.001	0.1	0.1	
		5.5		0.001	0.1	0.1	
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 12\text{mA}$		0.36	0.44	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}$		0.36	0.44	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}^{(1)}$		0.36	0.44	
I _{IN} ⁽²⁾	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$, GND		±0.1	±1.0	μA
I _{OZ}	Maximum 3-STATE Leakage Current	5.5	$\begin{aligned} &V_{I}\left(OE\right)=V_{IL},V_{IH};\\ &V_{I}=V_{CC},GND;\\ &V_{O}=V_{CC},GND \end{aligned}$		±0.25	±2.5	μA
I _{OLD}	Minimum Dynamic	5.5	V _{OLD} = 1.65V Max.			75	mA
I _{OHD}	Output Current ⁽³⁾	5.5	V _{OHD} = 3.85V Min.			-75	mA
I _{CC} ⁽²⁾	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		4.0	40.0	μA

Notes:

- 1. All outputs loaded; thresholds on input associated with output under test.
- 2. I_{IN} and I_{CC} @ 3.0V are guaranteed to be less than or equal to the respective limit @ 5.5V V_{CC} .
- 3. Maximum test duration 2.0ms, one output loaded at a time.

DC Electrical Characteristics for ACT

				T _A = -	+25°C	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	
Symbol	Parameter	V _{CC} (V)	Conditions	Тур.	G	uaranteed Limits	Units
V _{IH}	Minimum HIGH Level	4.5	$V_{OUT} = 0.1V$ or	1.5	2.0	2.0	V
	Input Voltage	5.5	V _{CC} – 0.1V	1.5	2.0	2.0	
V _{IL}	Maximum LOW	4.5	$V_{OUT} = 0.1V$ or	1.5	8.0	0.8	V
	Level Input Voltage	5.5	V _{CC} – 0.1V	1.5	0.8	0.8	
V _{OH}	Minimum HIGH Level	4.5	$I_{OUT} = -50\mu A$	4.49	4.4	4.4	V
	Output Voltage	5.5		5.49	5.4	5.4	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}$		3.86	3.76	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}^{(4)}$		4.86	4.76	
V _{OL}	Maximum LOW	4.5	I _{OUT} = 50μA	0.001	0.1	0.1	V
	Level Output Voltage	5.5		0.001	0.1	0.1	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}$		0.36	0.44	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}^{(4)}$		0.36	0.44	
I _{IN}	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$, GND		±0.1	±1.0	μA
I _{OZ}	Maximum 3-STATE Leakage Current	5.5	$V_I = V_{IL}, V_{IH};$ $V_O = V_{CC}, GND$		±0.25	±2.5	μA
I _{CCT}	Maximum I _{CC} /Input	5.5	$V_I = V_{CC} - 2.1V$	0.6		1.5	mA
I _{OLD}	Minimum Dynamic	5.5	V _{OLD} = 1.65V Max.			75	mA
I _{OHD}	Output Current ⁽⁵⁾	5.5	$V_{OHD} = 3.85V$ Min.			-75	mA
I _{CC}	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		4.0	40.0	μA

Notes:

- 4. All outputs loaded; thresholds on input associated with output under test.
- 5. Maximum test duration 2.0ms, one output loaded at a time.

AC Electrical Characteristics for AC

			T _A = +25°C, C _L = 50pF			$T_A = -40^{\circ}$ $C_L =$		
Symbol	Parameter	$V_{CC}(V)^{(6)}$	Min.	Тур.	Max.	Min.	Max.	Units
f _{MAX}	Maximum Clock Frequency	3.3	60	110		60		MHz
		5.0	100	155		100		
t _{PLH}	Propagation Delay,	3.3	3.0	11.0	13.5	1.5	15.5	ns
	CP to O _n	5.0	2.5	8.0	9.5	1.5	10.5	
t _{PHL}	Propagation Delay,	3.3	2.5	10.0	12.5	2.0	14.0	ns
	CP to O _n	5.0	2.0	7.0	9.0	1.5	10.0	
t _{PZH}	Output Enable Time	3.3	3.0	9.5	11.5	1.5	13.0	ns
		5.0	2.0	7.0	8.5	1.0	9.5	
t _{PZL}	Output Enable Time	3.3	2.5	9.0	11.5	1.5	13.0	ns
		5.0	2.0	6.5	8.5	1.0	9.5	
t _{PHZ}	Output Disable Time	3.3	3.0	10.5	12.5	2.0	14.5	ns
		5.0	2.0	8.0	11.0	2.0	12.5	
t _{PLZ}	Output Disable Time	3.3	2.0	8.0	11.5	1.0	12.5	ns
		5.0	1.5	6.5	8.5	1.0	10.0	

Note:

6. Voltage range 3.3 is 3.3V \pm 0.3V. Voltage range 5.0 is 5.0V \pm 0.5V.

AC Operating Requirements for AC

			T _A = + C _L =	-25°C, 50pF	$T_A = -40$ °C to +85°C, $C_L = 50$ pF	
Symbol	Parameter	$V_{CC}(V)^{(7)}$	Тур.	Gu	aranteed Minimum	Units
t _S	Setup Time, HIGH or LOW,	3.3	2.0	5.5	6.0	ns
	D _n to CP	5.0	1.0	4.0	4.5	
t _H	Hold Time, HIGH or LOW,	3.3	-1.0	1.0	1.0	ns
	D _n to CP		0	1.5	1.5	
t _W	CP Pulse Width, HIGH or LOW	3.3	4.0	5.5	6.0	ns
		5.0	2.5	4.0	4.5	

Note:

7. Voltage range 3.3 is 3.3V \pm 0.3V. Voltage range 5.0 is 5.0V \pm 0.5V.

AC Electrical Characteristics for ACT

			T _A = +25°C, C _L = 50pF			$T_A = -40^{\circ}C$ $C_L =$		
Symbol	Parameter	$V_{CC}(V)^{(8)}$	Min.	Тур.	Max.	Min.	Max.	Units
f _{MAX}	Maximum Clock Frequency	5.0	100	160		90		MHz
t _{PLH}	Propagation Delay, CP to O _n	5.0	2.0	8.5	10.0	2.0	11.5	ns
t _{PHL}	Propagation Delay, CP to O _n	5.0	2.0	8.0	9.5	1.5	11.0	ns
t _{PZH}	Output Enable Time	5.0	2.0	8.0	9.5	1.5	10.5	ns
t _{PZL}	Output Enable Time	5.0	1.5	8.0	9.0	1.5	10.5	ns
t _{PHZ}	Output Disable Time	5.0	1.5	8.5	11.5	1.0	12.5	ns
t _{PLZ}	Output Disable Time	5.0	1.5	7.0	8.5	1.0	10.0	ns

Note:

8. Voltage range 5.0 is $5.0V \pm 0.5V$.

AC Operating Requirements for ACT

				T _A = +	⊦25°C, 50pF	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C},$ $C_L = 50\text{pF}$	
Symbol	Parameter	V	_{CC} (V) ⁽⁹⁾	Тур.	Gua	aranteed Minimum	Units
t _S	Setup Time, HIGH or LOW, D _n to CP		5.0	1.0	5.5	5.5	ns
t _H	Hold Time, HIGH or LOW, D _n to CP		5.0	0	1.5	1.5	ns
t _W	CP Pulse Width, HIGH or LOW		5.0	2.5	5.0	5.0	ns

Note:

9. Voltage range 5.0 is $5.0V \pm 0.5V$.

Capacitance

Symbo	l Parameter	Conditions	Тур.	Units
C _{IN}	Input Capacitance	V _{CC} = OPEN	4.5	pF

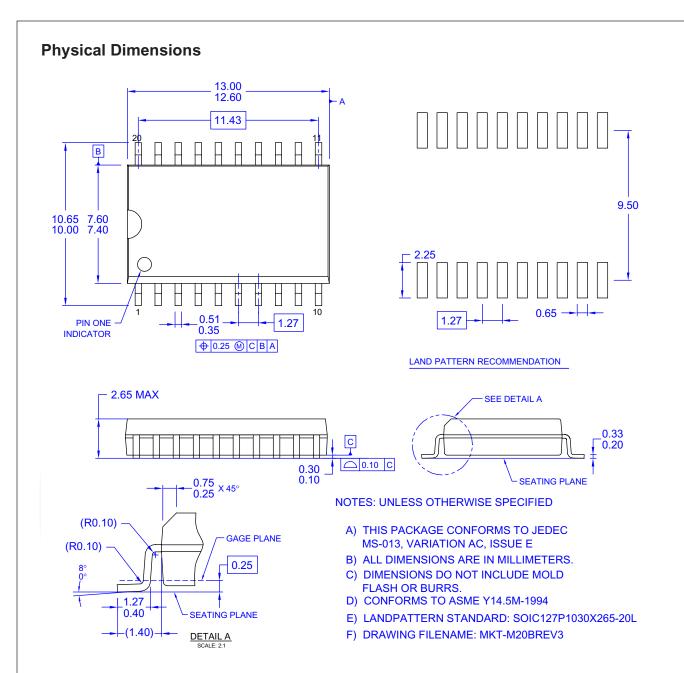
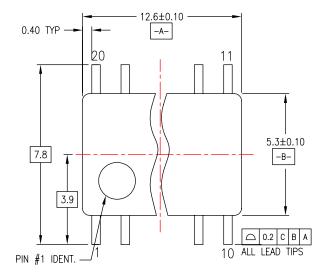
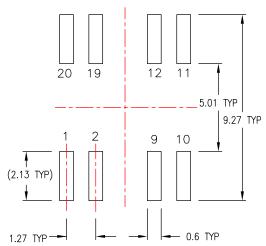


Figure 1. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide

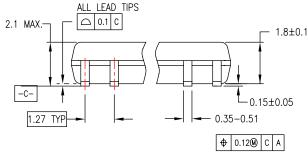
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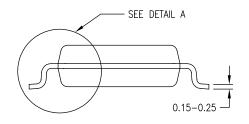
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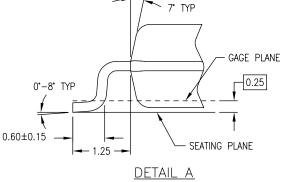




DIMENSIONS ARE IN MILLIMETERS

NOTES:

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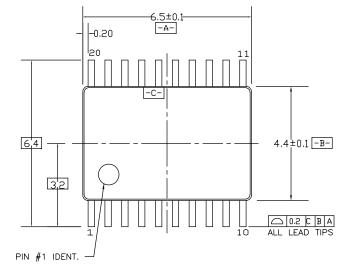
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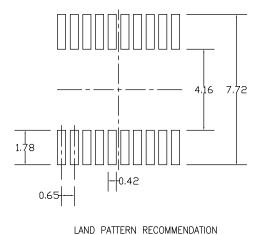
Figure 2. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

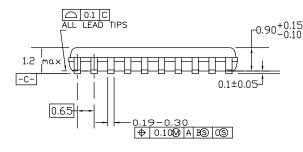
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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

0.09-0.20¹ 12.00° GAGE PLANE 0.6±0.1 R0.09min SEATING PLANE R0.09min

SEE DETAIL A

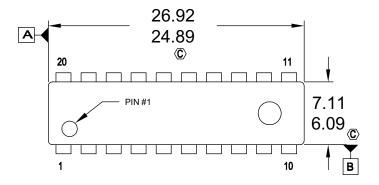
DETAIL A

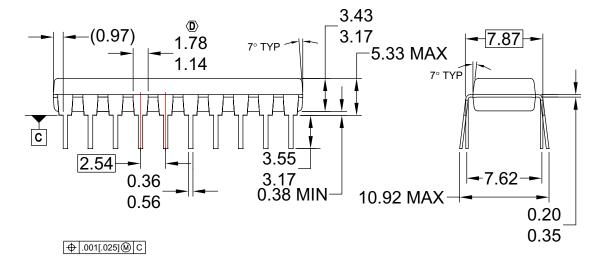
MTC20REVD1

Figure 3. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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NOTES:
A. CONFORMS TO JEDEC REGISTRATION MS-001,
VARIATIONS AD.

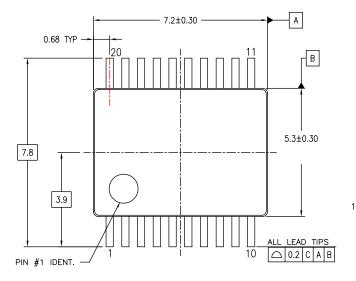
- **B. ALL DIMENSIONS ARE IN MILLIMETERS**
- © DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
 MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED
- 0.25MM.

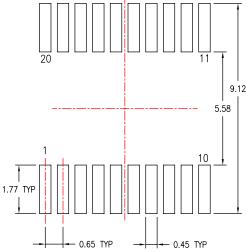
 D. DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED
- E. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- F. DRAWING FILE NAME: N20AREV8

Figure 4. 20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

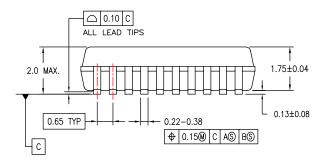
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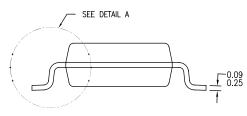
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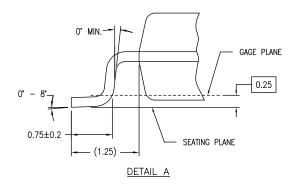




DIMENSIONS ARE IN MILLIMETERS

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- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ASME Y14.5M 1994.



MSA20REVB

Figure 5. 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide

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QFET[®] QS™

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